PC	N Number:	20190405000.0			PCN Dat	April	April 08, 2019					
Title: Datasheet for ADS8864												
Cu	stomer Contact:		CN Manager				Dept:			t: Quality Services		
Change Type:												
	Assembly Site			Design				١	Wafer	Bump Site		
	Assembly Process	☐ Data Sheet			et			Wafer Bump Material				
	Assembly Materials			Part number change				١	Wafer Bump Process			
	Mechanical Specification			Test Site				_	Wafer Fab Site			
	Packing/Shipping/Labeling			Test Process				_	Wafer Fab Materials			
	☐ Wafer Fab Process											
Notification Details												
Description of Change:												
Texas Instruments Incorporated is announcing an information only notification.												
The product datasheet(s) is being updated as summarized below.  The following change history provides further details.												
•												
- U	Texas Instruments									Al	DS8864	
_	INSTRUMENTS						S	BAS	3572B -	MAY 2013-REVISED MA	RCH 2019	
Cha	nges from Revision A (D	ecember 2013	) to	Revision B							Page	
	Added Davice Information	table ESD Pa	tings	table Pecer	mandad Ona	ratina	Cond	itio	ac table	Darametric		
	Added Device Information table, ESD Ratings table, Recommended Operating Conditions table, Parametric Measurement Information section, Feature Description section, Device Functional Modes section, Application and											
1	Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation											
	Support section, and Mechanical, Packaging, and Orderable Information section											
	Changed analog input from pseudo-differential to single-ended throughout document											
	Changed MSOP to VSSOP throughout document											
	Changed title of Device Comparison Table from Family Information											
	Changed footnotes of Family Information table											
	Changed LSB footnote in Electrical Characteristics table to include how to convert LSB to ppm											
	or and the second secon											
	Changed Charge-Kickback Filter section title and functionality description											
			_									
The	datasheet number v	vill be chang	ging	l <b>.</b>								
De	evice Family				Chan	ige F	rom:			Change To:		
Δ	DS8864				SBAS	5572	Α			SBAS572B		
These changes may be reviewed at the datasheet links provided.												
, ,												
http://www.ti.com/product/ADS8864												
Reason for Change:												
To accurately reflect device characteristics.												
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):												
No anticipated impact. This is a specification change announcement only. There are no changes to												
the actual device.												
Changes to product identification resulting from this PCN:												
None.												
	oduct Affected:											
	DS8864IDGS	ADS886	410	)GSR	ADS886	41DP	CR			ADS8864IDRCT		
1 4	22000-IDQ2	1 453000	, TIL	, J J I I	UD 2000	LIDI	~ · · ·		1	" NOTOTOTION CI		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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